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# ANNOUNCEMENTS

## Tenth International Thermal Expansion Symposium
**Boulder, Colorado, U.S.A.**
**June 6–7, 1989**

This is the tenth symposium of this series on thermal expansion. The goal of the symposium is to communicate up-to-date information on theoretical and experimental aspects of thermal expansion, including applications dealing with materials in all temperature ranges.

The symposium is sponsored by the National Institute of Standards and Technology.

Abstracts (200–300 words) must be submitted by February 17, 1989. Manuscripts must be submitted by June 7, 1989. They will be reviewed and those accepted will be published in a special proceedings issue of the *International Journal of Thermophysics.*

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## Second Asian Thermophysical Properties Conference
**Hokkaido University, Sapporo, Japan**
**September 20–22, 1989**

The conference will cover both theoretical and experimental aspects of the thermophysical properties of solids, liquids, and gases. The topics will include transport, thermodynamic, and thermal radiative properties; measurement techniques and instrumentation; and data prediction, correlation, and evaluation, standard reference data, and data bases.

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The conference chairmen are Professor Nobuhiro Seki of Hokkaido University (Japan) and Professor Bu-Xuang Wang of Tsinghua University (PRC).

The official language of the conference is English.

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